# **Power MOSFET**

60 V, 295 mA, Dual N–Channel with ESD Protection, SC–88

### Features

- Low R<sub>DS(on)</sub>
- Low Gate Threshold
- Low Input Capacitance
- ESD Protected Gate
- This is a Pb–Free Device

## Applications

- Low Side Load Switch
- DC–DC Converters (Buck and Boost Circuits)

### **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}C$ unless otherwise stated)

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Parame	Symbol	Value	Units			
Drain-to-Source Voltage	V <sub>DSS</sub>	60	V			
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V	
Continuous Drain	Steady	$T_A = 25^{\circ}C$	۱ <sub>D</sub>	295	mA	
Current (Note 1)	State	$T_A = 85^{\circ}C$		212		
	t ≤ 5 s	$T_A = 25^{\circ}C$	1	304		
		$T_A = 85^{\circ}C$	1	219		
Power Dissipation (Note 1)	Steady State	$T_A = 25^{\circ}C$	P <sub>D</sub>	250	mW	
	t ≤ 5 s			266		
Pulsed Drain Current	t <sub>p</sub> =	= 10 μs	I <sub>DM</sub>	900	mA	
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C	
Source Current (Body Diode)		۱ <sub>S</sub>	210	mA		
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		ΤL	260	°C		
Gate–Source ESD Rating (HBM, Method 3015)			ESD	1400	V	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Units
Junction-to-Ambient - Steady State	$R_{\theta JA}$	500	°C/W
Junction-to-Ambient – t $\leq$ 5 s	$R_{\theta J A}$	470	

1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).

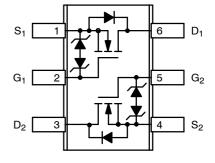


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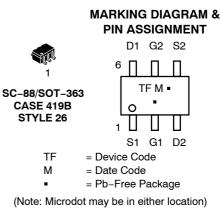
#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> Max
60 V	1.6 Ω @ 10 V	295 mA
	2.5 Ω @ 4.5 V	293 1114





Top View



## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTJD5121NT1G	SC-88 (Pb-Free)	3000 / Tape & Reel
NTJD5121NT2G	SC-88 (Pb-Free)	3000 / Tape & Reel

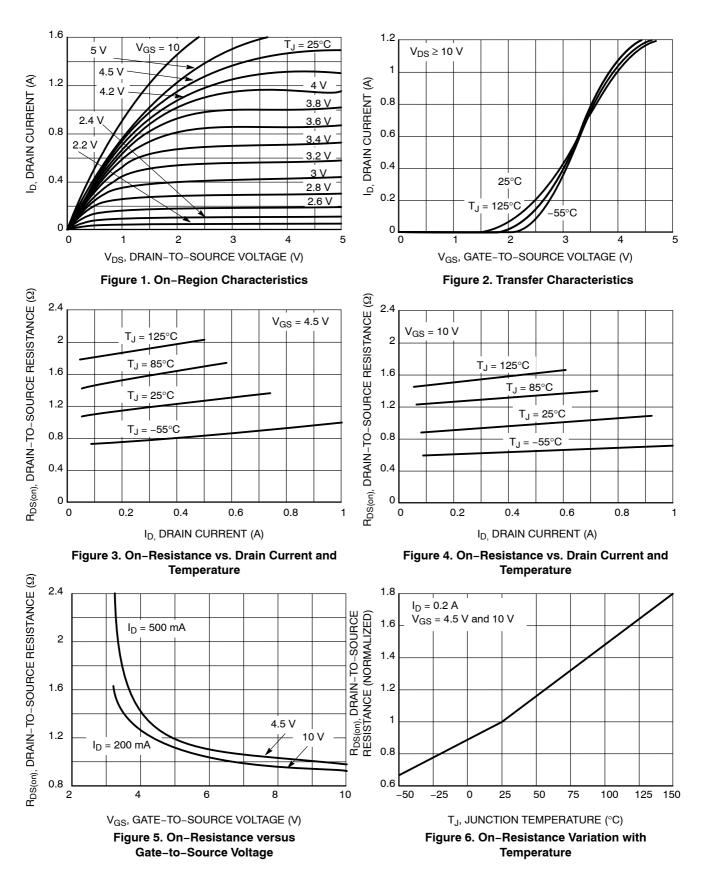
+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

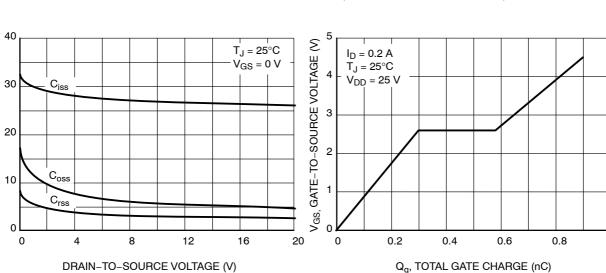
# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Мах	Unit
OFF CHARACTERISTICS	· · · · ·				-	-	-
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 250 µA		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA, r	ef to 25°C		92		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub> V <sub>GS</sub> = 0 V,		$T_J = 25^{\circ}C$			1.0	μΑ
		$V_{\rm DS} = 60  \rm V$	T <sub>J</sub> = 125°C			500	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>C</sub>	<sub>as</sub> = ±20 V			±10	μA
ON CHARACTERISTICS (Note 2)	•						-
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{DS}$	o = 250 μA	1.0	1.7	2.5	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				4.0		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 500 mA			1.0	1.6	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>[</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 200 mA		1.2	2.5	
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 200 mA			80		S
CHARGES AND CAPACITANCES	•						-
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 20 V			26		pF
Output Capacitance	C <sub>OSS</sub>				4.4		
Reverse Transfer Capacitance	C <sub>RSS</sub>				2.5		
Total Gate Charge	Q <sub>G(TOT)</sub>				0.9		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V, V	ν <sub>DS</sub> = 25 V,		0.2		1
Gate-to-Source Charge	Q <sub>GS</sub>	$I_D = 200$	) mA		0.3		
Gate-to-Drain Charge	Q <sub>GD</sub>		Ē		0.28		
SWITCHING CHARACTERISTICS (No	ote 3)						-
Turn-On Delay Time	t <sub>d(on)</sub>				22		ns
Rise Time	t <sub>r</sub>	$V_{GS}$ = 4.5 V, $V_{DD}$ = 25 V, I <sub>D</sub> = 200 mA, R <sub>G</sub> = 25 $\Omega$			34		
Turn-Off Delay Time	t <sub>d(off)</sub>				34		1
Fall Time	t <sub>f</sub>				32		1
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	$T_J = 25^{\circ}C$		0.8	1.2	V
		$I_{\rm S} = 200 \text{ mA}$ $T_{\rm J} = 85^{\circ}\text{C}$			0.7		-

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.

#### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)





# TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)



C, CAPACITANCE (pF)

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

1

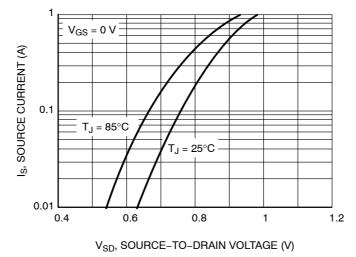
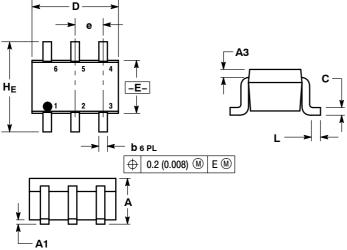


Figure 9. Diode Forward Voltage vs. Current

#### PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W** 



NOTES: DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

CONTROLLING DIMENSION: INCH. 419B-01 OBSOLETE, NEW STANDARD 419B-02. 2.

3

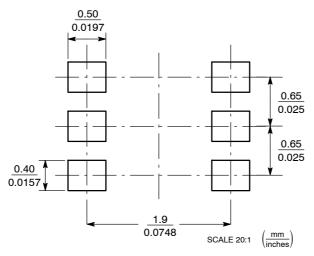
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.95	1.10	0.031	0.037	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.20 REF			(	0.008 RI	EF	
b	0.10	0.21	0.30	0.004	0.008	0.012	
С	0.10	0.14	0.25	0.004	0.005	0.010	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65 BSC			0.026 BSC			
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	2.00	2.10	2.20	0.078	0.082	0.086	

STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2

4. SOURCE 2 5. GATE 2

6. DRAIN 1

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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